$4 \text{ M SRAM} (512\text{-kword} \times 8\text{-bit})$

HITACHI

ADE-203-640B (Z) Rev. 2.0 Nov. 1997

Description

The Hitachi HM628512A is a 4-Mbit static RAM organized 512-kword \times 8-bit. It realizes higher density, higher performance and low power consumption by employing 0.5 μ m Hi-CMOS process technology. The device, packaged in a 525-mil SOP (foot print pitch width) or 400-mil TSOP TYPE II or 600-mil plastic DIP, is available for high density mounting. The HM628512A is suitable for battery backup system.

Features

• Single 5 V supply

• Access time: 55/70 ns (max)

Power dissipation

— Active: 50 mW/MHz (typ)

— Standby: 10 μW (typ)

• Completely static memory. No clock or timing strobe required

• Equal access and cycle times

Common data input and output: Three state output

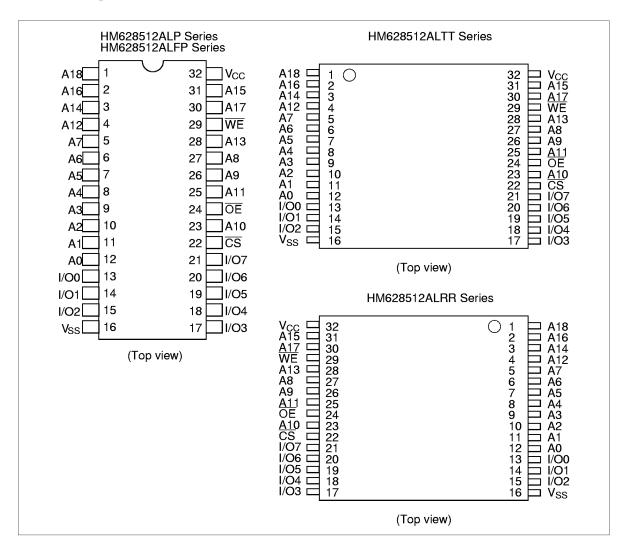
• Directly TTL compatible: All inputs and outputs

Battery backup operation

Ordering Information

Type No.	Access time	Package
HM628512ALP-5 HM628512ALP-7	55 ns 70 ns	600-mil 32-pin plastic DIP (DP-32)
HM628512ALP-5SL HM628512ALP-7SL	55 ns 70 ns	
HM628512ALFP-5 HM628512ALFP-7	55 ns 70 ns	525-mil 32-pin plastic SOP (FP-32D)
HM628512ALFP-5SL HM628512ALFP-7SL	55 ns 70 ns	_
HM628512ALTT-5 HM628512ALTT-7	55 ns 70 ns	400-mil 32-pin plastic TSOP II (TTP-32D)
HM628512ALTT-5SL HM628512ALTT-7SL	55 ns 70 ns	_
HM628512ALRR-5 HM628512ALRR-7	55 ns 70 ns	400-mil 32-pin plastic TSOP II reverse (TTP-32DR)
HM628512ALRR-5SL HM628512ALRR-7SL	55 ns 70 ns	

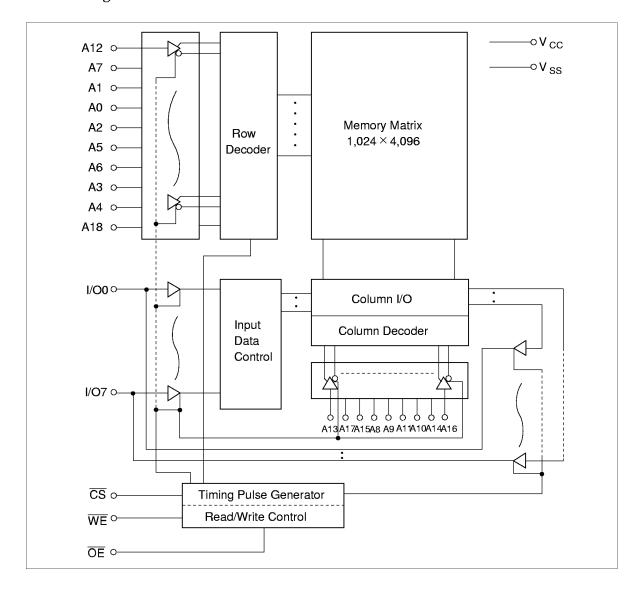
Pin Arrangement



Pin Description

Pin name	Function
A0 to A18	Address input
I/O0 to I/O7	Data input/output
CS	Chip select
ŌĒ	Output enable
WE	Write enable
V _{cc}	Power supply
V _{SS}	Ground

Block Diagram



Function Table

WE	CS	ŌE	Mode	V _{cc} current	Dout pin	Ref. cycle
×	Н	×	Not selected	I_{SB}, I_{SB1}	High-Z	_
Н	L	Н	Output disable	I _{cc}	High-Z	_
Н	L	L	Read	I _{cc}	Dout	Read cycle
L	L	Н	Write	I _{cc}	Din	Write cycle (1)
L	L	L	Write	I _{cc}	Din	Write cycle (2)

Note: ×: H or L

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Power supply voltage	V _{cc}	-0.5 to +7.0	V
Voltage on any pin relative to V _{ss}	V _T	-0.5^{*1} to $V_{cc} + 0.3^{*2}$	V
Power dissipation	P _T	1.0	W
Operating temperature	Topr	0 to +70	°C
Storage temperature	Tstg	-55 to +125	°C
Storage temperature under bias	Tbias	−10 to +85	°C

Notes: 1. -3.0 V for pulse half-width ≤ 30 ns

2. Maximum voltage is 7.0 V

Recommended DC Operating Conditions (Ta = 0 to +70°C)

Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage	V _{cc}	4.5	5.0	5.5	V
	V _{ss}	0	0	0	V
Input high voltage	V _{IH}	2.2	_	V _{cc} + 0.3	V
Input low voltage	V _{IL}	-0.3 ^{*1}	_	0.8	V

Note: 1. -3.0 V for pulse half-width ≤ 30 ns

DC Characteristics (Ta = 0 to +70°C, $V_{\rm CC}$ = 5 V $\pm 10\%$, V_{SS} = 0 V)

Parameter		Symbol	Min	Typ*1	Max	Unit	Test conditions
Input leakage current		I _{LI}	_	_	1	μΑ	Vin = V _{SS} to V _{CC}
Output leakage current		I _{LO}	_	_	1	μА	$\overline{\overline{CS}} = V_{IH} \text{ or } \overline{\overline{OE}} = V_{IH} \text{ or } \overline{WE} = V_{IL}, V_{I/O} = V_{SS} \text{ to } V_{CC}$
Operating power supply current: DC		I _{cc}	_	8	15	mA	$\overline{CS} = V_{IL},$ others = V_{IH}/V_{IL} , $I_{I/O} = 0$ mA
Operating power supply current	HM628512A-5	I _{CC1}	_	45	70	mA	$\frac{\text{Min cycle, duty} = 100\%}{\overline{\text{CS}}} = \text{V}_{\text{IL}}, \text{ others} = \text{V}_{\text{IH}}/\text{V}_{\text{IL}} \\ \text{I}_{\text{I/O}} = 0 \text{ mA}$
	HM628512A-7	I _{CC1}	_	40	60	mA	_
Operating power supply current		I _{CC2}	_	10	20	mA	$\begin{split} & \text{Cycle time} = 1 \ \mu\text{s}, \\ & \text{duty} = 100\% \\ & I_{\text{I/O}} = 0 \ \text{mA}, \ \overline{\text{CS}} \leq 0.2 \ \text{V} \\ & V_{\text{IH}} \geq V_{\text{CC}} - 0.2 \ \text{V}, \ V_{\text{IL}} \leq 0.2 \ \text{V} \\ & \text{V} \end{split}$
Standby power supply curr	ent: DC	I _{SB}	_	1	3	mA	CS = V _{IH}
Standby power supply current (1): DC		I _{SB1}	_	2*2	100*2	μΑ	$Vin \ge 0 \text{ V}, \overline{CS} \ge V_{CC} - 0.2 \text{ V}$
			_	2*3	50* ³	μΑ	-
Output low voltage		V _{oL}	_	_	0.4	٧	I _{OL} = 2.1 mA
Output high voltage		V_{OH}	2.4		_	٧	I _{OH} = -1.0 mA

Notes: 1. Typical values are at $V_{\text{CC}} = 5.0 \text{ V}$, $Ta = +25^{\circ}\text{C}$ and specified loading, and not guaranteed.

- 2. This characteristics is guaranteed only for L version.
- 3. This characteristics is guaranteed only for L-SL version.

Capacitance (Ta = 25°C, f = 1 MHz)

Parameter	Symbol	Тур	Max	Unit	Test conditions
Input capacitance*1	Cin	_	8	рF	Vin = 0 V
Input/output capacitance*1	CINO	_	10	pF	$V_{I/O} = 0 V$

Note: 1. This parameter is sampled and not 100% tested.

AC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V ± 10%, unless otherwise noted.)

Test Conditions

• Input pulse levels: 0.8 V to 2.4 V

• Input rise and fall time: 5 ns

Input and output timing reference levels: 1.5 V

• Output load: $1 \text{ TTL Gate} + C_L (100 \text{ pF}) (HM628512A-7)$

 $1 \text{ TTL Gate} + C_L (50 \text{ pF}) (HM628512A-5)$

(Including scope & jig)

Read Cycle

		HIVI62	8512A				
		-5		-7		_	
Parameter	Symbol	Min	Max	Min	Max	— Unit	Notes
Read cycle time	t _{RC}	55	_	70		ns	
Address access time	t _{AA}	_	55	_	70	ns	
Chip select access time	t _{co}	_	55	_	70	ns	
Output enable to output valid	t _{oe}	_	25	_	35	ns	
Chip selection to output in low-Z	t _{LZ}	10	_	10		ns	2
Output enable to output in low-Z	t _{oLZ}	5	_	5	_	ns	2
Chip deselection to output in high-Z	t _{HZ}	0	20	0	25	ns	1, 2
Output disable to output in high-Z	t _{oHZ}	0	20	0	25	ns	1, 2
Output hold from address change	t _{oн}	10	_	10	_	ns	

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Write Cycle

HM628512A

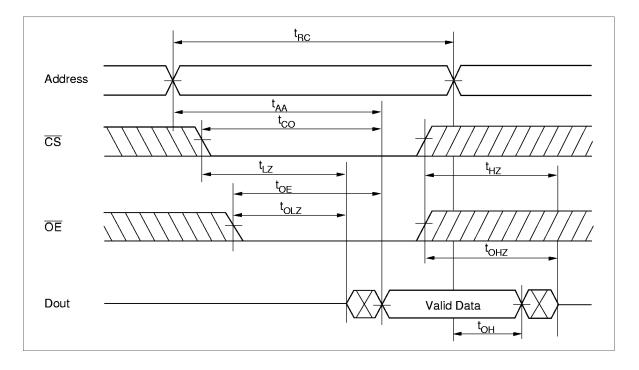
		-5		-7		_	
Parameter	Symbol	Min	Max	Min	Max	— Unit	Notes
Write cycle time	t _{wc}	55	_	70	_	ns	
Chip selection to end of write	t _{cw}	50	_	60	_	ns	4
Address setup time	t _{AS}	0		0		ns	5
Address valid to end of write	t _{aw}	50		60	_	ns	
Write pulse width	t _{wP}	40	_	50	_	ns	3, 12
Write recovery time	t _{wR}	0	_	0		ns	6
WE to output in high-Z	t _{wHZ}	0	20	0	25	ns	1, 2, 7
Data to write time overlap	t _{DW}	25	_	30	_	ns	
Data hold from write time	t _{DH}	0		0		ns	
Output active from output in high-Z	t _{ow}	5	_	5	_	ns	2
Output disable to output in high-Z	t _{oHZ}	0	20	0	25	ns	1, 2, 7

Notes: 1. t_{HZ} , t_{OHZ} and t_{WHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

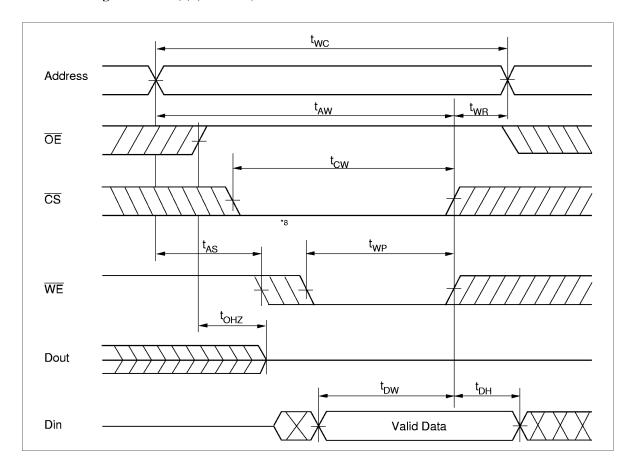
- 2. This parameter is sampled and not 100% tested.
- 3. A write occurs during the overlap (t_{WP}) of a low \(\overline{CS}\) and a low \(\overline{WE}\). A write begins at the later transition of \(\overline{CS}\) going low or \(\overline{WE}\) going low. A write ends at the earlier transition of \(\overline{CS}\) going high or \(\overline{WE}\) going high. t_{WP} is measured from the beginning of write to the end of write.
- 4. $\,t_{_{CW}}$ is measured from $\overline{\mbox{CS}}$ going low to the end of write.
- 5. t_{AS} is measured from the address valid to the beginning of write.
- 6. t_{wR} is measured from the earlier of \overline{WE} or \overline{CS} going high to the end of write cycle.
- 7. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.
- 8. If the $\overline{\text{CS}}$ low transition occurs simultaneously with the $\overline{\text{WE}}$ low transition or after the $\overline{\text{WE}}$ transition, the output remain in a high impedance state.
- 9. Dout is the same phase of the write data of this write cycle.
- 10. Dout is the read data of next address.
- 11. If CS is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the outputs must not be applied to them.
- 12. In the write cycle with \overline{OE} low fixed, t_{WP} must satisfy the following equation to avoid a problem of data bus contention. $t_{WP} \ge t_{DW} \min + t_{WHZ} \max$

Timing Waveforms

Read Timing Waveform $(\overline{WE} = V_{IH})$

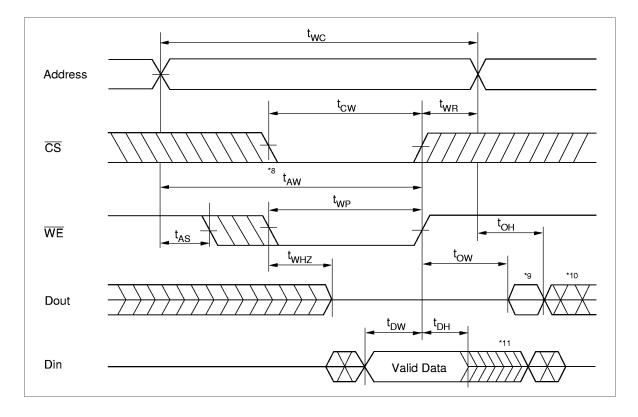


Write Timing Waveform (1) $(\overline{OE} Clock)$



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Write Timing Waveform (2) (OE Low Fixed)



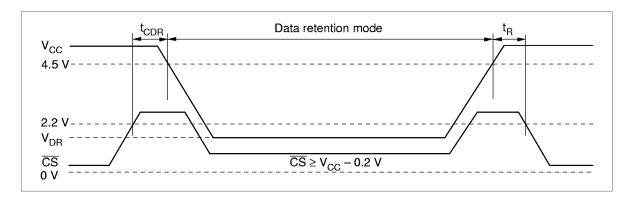
Low V_{CC} **Data Retention Characteristics** ($Ta = 0 \text{ to } +70^{\circ}\text{C}$)

Parameter	Symbol	Min	Тур	Max	Unit	Test conditions*3
V _{cc} for data retention	V_{DR}	2	_	_	٧	$\overline{\text{CS}} \ge \text{V}_{\text{CC}} - 0.2 \text{ V, Vin} \ge 0 \text{ V}$
Data retention current	I _{CCDR}	_	1*4	50* ¹	μΑ	$\frac{V_{CC}}{CS}$ = 3.0 V, Vin \geq 0 V $\frac{V_{CC}}{CS} \geq V_{CC} - 0.2$ V
		_	1*4	15* ²	μΑ	
Chip deselect to data retention time	t _{cdr}	0	_	_	ns	See retention waveform
Operation recovery time	t _R	5	_	_	ms	

Notes: 1. For L-version and 20 μ A (max.) at Ta = 0 to 40°C.

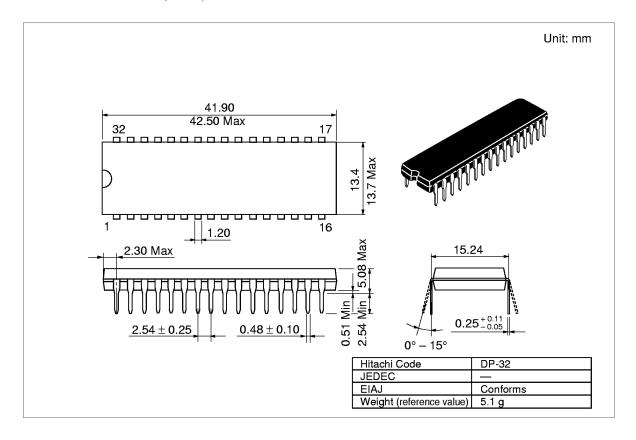
- 2. For SL-version and 3 μ A (max.) at Ta = 0 to 40°C.
- 3. $\overline{\text{CS}}$ controls address buffer, $\overline{\text{WE}}$ buffer, $\overline{\text{OE}}$ buffer, and Din buffer. In data retention mode, Vin levels (address, $\overline{\text{WE}}$, $\overline{\text{OE}}$, I/O) can be in the high impedance state.
- 4. Typical values are at $V_{\rm CC}$ = 3.0 V, Ta = 25°C and specified loading, and not guaranteed.

$Low~V_{CC}~Data~Retention~Timing~Waveform~(\overline{CS}~Controlled)$



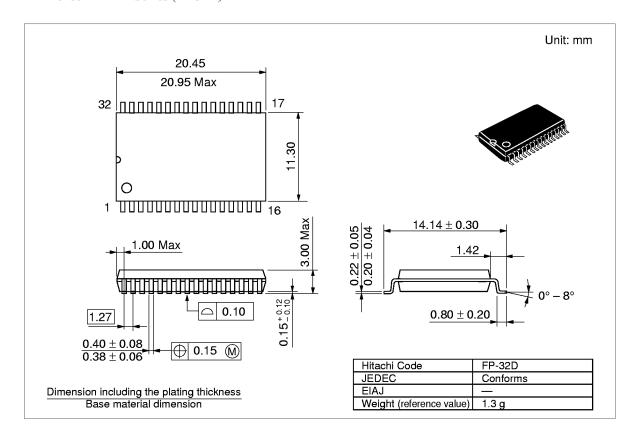
Package Dimensions

HM628512ALP Series (DP-32)



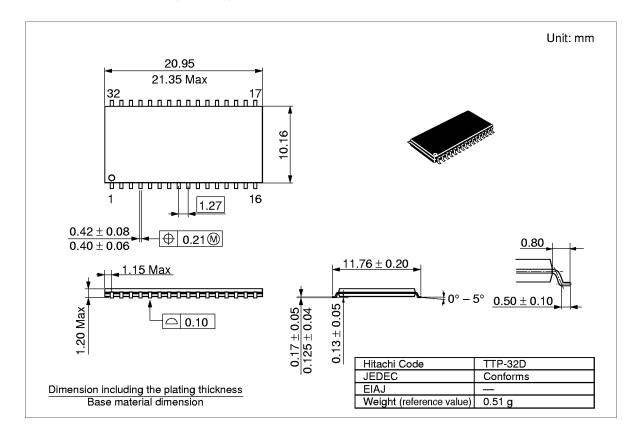
Package Dimensions (cont.)

HM628512ALFP Series (FP-32D)



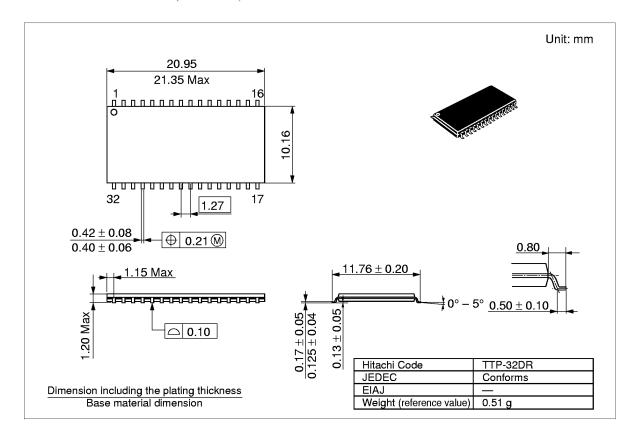
Package Dimensions (cont.)

HM628512ALTT Series (TTP-32D)



Package Dimensions (cont.)

HM628512ALRR Series (TTP-32DR)



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